# **TOSHIBA**



The information contained herein is subject to change without notice. 021023 D

TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress.

It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications.

Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc. 021023 A

The Toshiba products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.).

These Toshiba products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc. Unintended Usage of Toshiba products listed in this document shall be made at the customer's own risk. 021023\_B

The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations. 060106 Q

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others. 021023\_C

The products described in this document may include products subject to the foreign exchange and foreign trade laws. 021023\_F

For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions. 030619 S

# Revision History

Date	Revision	
2003/6/23	1	First Release
2008/8/29	2	Contents Revised



## Caution in Setting the UART Noise Rejection Time

When UART is used, settings of RXDNC are limited depending on the transfer clock specified by BRG. The combination "O" is available but please do not select the combination "-".

The transfer clock generated by timer/counter interrupt is calculated by the following equation:

Transfer clock [Hz] = Timer/counter source clock [Hz] ÷ TTREG set value

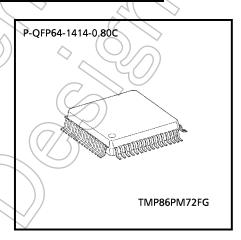
		RXDNC setting					
BRG setting	Transfer clock [Hz]	00 (No noise rejection)	01 (Reject pulses shorter than 31/fc[s] as noise)	10 (Reject pulses shorter than 63/fc[s] as noise)	11 (Reject pulses shorter than 127/fc[s] as noise)		
000	fc/13	0	0	0	<u> </u>		
110	fc/8	0	(7/4)	- 6	→ -		
(When the transfer clock gen- erated by timer/counter inter-	fc/16	0	000	<b>\$</b> -\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	/		
rupt is the same as the right side column)	fc/32	0	0	0	_		
The setting except the	above	0			0		

CMOS 8-Bit Microcontroller

## TMP86PM72FG

The TMP86PM72 is a OTP type MCU which includes 32-Kbyte one-time PROM. It is a pin compatible with a mask ROM product of the TMP86CH72/CM72. Writing the program to built-in PROM, the TMP86PM72 operates as the same way as the TMP86CH72/CM72. Using the Adapter socket, you can write and verify the data for the TMP86PM72 with a general-purpose PROM programmer same as TC571000D/AD.

Product No.	OTP	RAM	Package	Adapter Socket
TMP86PM72FG	32 K × 8 bits	1 K × 8 bits	P-QFP64-1414-0.80C	BM11707



030619EBP1

The information contained herein is subject to change without notice.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others.

TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..

The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer of the products of the product of the products of the products of the product of the products of the products of the products of the product of the products of the product of

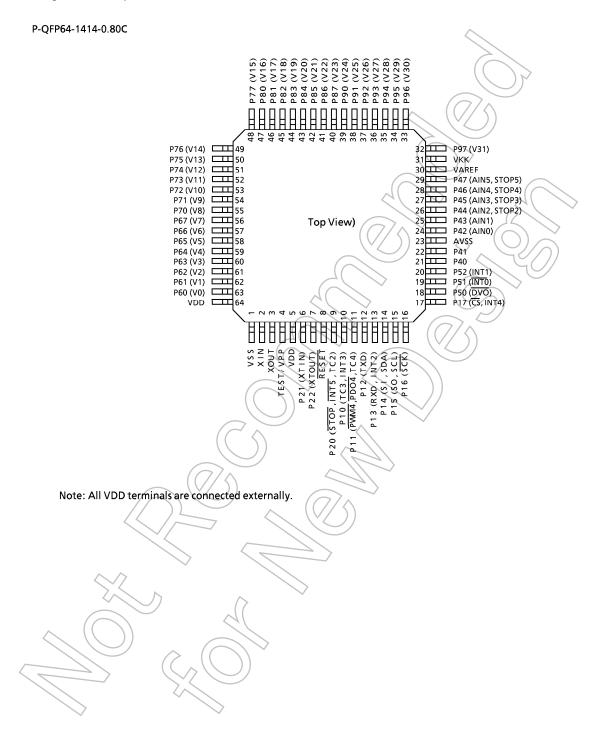
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, applicable instruments. transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- TOSHIBA products should not be embedded to the downstream products which are prohibited to be produced and sold, under any law and regulations.
- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.



Purchase of TOSHIBA I<sup>2</sup> C components conveys a license under the Philips I<sup>2</sup> C Patent Rights to use these components in an I<sup>2</sup> C system, provided that the system conforms to the I<sup>2</sup> C Standard Specification as defined by

> 86PM72-1 2003-06-23

#### Pin Assignments (Top View)



86PM72-2 2003-06-23

#### **Pin Function**

The TMP86PM72 has MCU mode and PROM mode.

(1) MCU mode

In the MCU mode, the TMP86PM72 is a pin compatible with the TMP86CH72/CM72 (Make sure to fix the TEST pin to low level).

(2) PROM mode

Pin name (PROM mode)	Input/Output	Functions	Pin Name (MCU mode)
A16 to A12			PD4 to PD0
A11 to A8	Input	Input of Memory address for program	P53 to P50
A7 to A0			P47 to P40
D7 to D0	I/O	Input/Output of Memory data for program	P17 to P10
CE		Chip enable	P95
ŌĒ	Input	Output enable	P94
PGM		Program control	P93
VPP		+ 12.75 V/5 V (Power supply of program)	TEST
VDD	Power supply	+ 6.25 V/5 V	VDD
GND		0 V (//)	VSS
P51, P21		PROM mode setting pin. Fix to high.	
P50, P20, P22, AVSS, VAREF	I/O	PROM mode setting pin. Fix to low.	
RESET			
XIN	Input	Self oscillation with resonator (10 MHz)	
XOUT	Output	Sen oscillation with resolution (10 MHz)	

### Operation

This section describes the functions and basic operational blocks of TMP86PM72.

The TMP86PM72 has PROM in place of the mask ROM which is included in the TMP86CH72/CM72.

In addition, TMP86PM72 operates as the single clock mode when releasing reset.

When using the dual clock mode, oscillate a low-frequency clock by [SET (SYSCR2). XTEN] command at the beginning of program.

## 1. Operating Mode

The TMP86PM72 has MCU mode and PROM mode.

#### 1.1 MCU Mode

The MCU mode is set by fixing the TEST/VPP pin to the low level. (TEST/VPP pin cannot be used open because it has no built-in pull-down resister).

### 1.1.1 Program Memory

The TMP86PM72 has a 32 Kbyte built-in one time PROM (addresses 8000<sub>H</sub> to FFFF<sub>H</sub> in the MCU mode, addresses 0000<sub>H</sub> to 7FFF<sub>H</sub> in the PROM mode).

When using TMP86PM72 for evaluation of mask ROM products, the program is written in the program storing area shown in Figure 1-1.

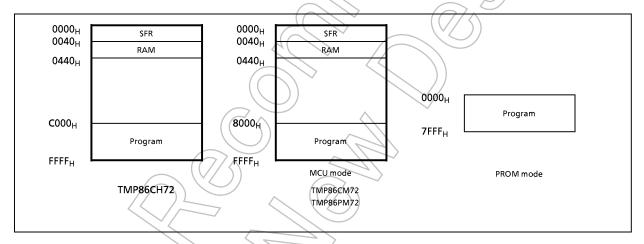


Figure 1-1. Program Memory Area

Note: The area that is not in use should be set data to FFH, or a general-purpose PROM programmer should be set only in the program memory area to access.

86PM72-4 2003-06-23

## 1.1.2 Data Memory

TMP86PM72 has a built-in 1 Kbyte Data memory (static RAM).

## 1.1.3 Input/Output Circuitry

(1) Control pins

The control pins of the TMP86PM72 are the same as those of the TMP86CH72/CM72 except that the TEST pin does not have a built-in pull-down resister.

(2) I/O ports

The I/O circuitries of TMP86PM72 I/O ports are the same as the those of TMP86CH72/CM72.



86PM72-5 2003-06-23

#### 1.2 PROM Mode

The PROM mode is set by setting the RESET pin, the ports P51, P50, P22 to P20 and TEST as shown in Figure 1-2. The programming and verification for the internal PROM is achieved by using a general-purpose PROM programmer with the adapter socket.

Note: The high-speed program mode can be used. The setting is different according to the type of PROM programmer to use, refer to each description of PROM programmer.

The TMP86PM72 does not support the electric signature mode, apply the ROM type of PROM programmer to TC571000D/AD.

Always set the switch of adapter socket to the N side when using TOSHIBA's adapter socket.

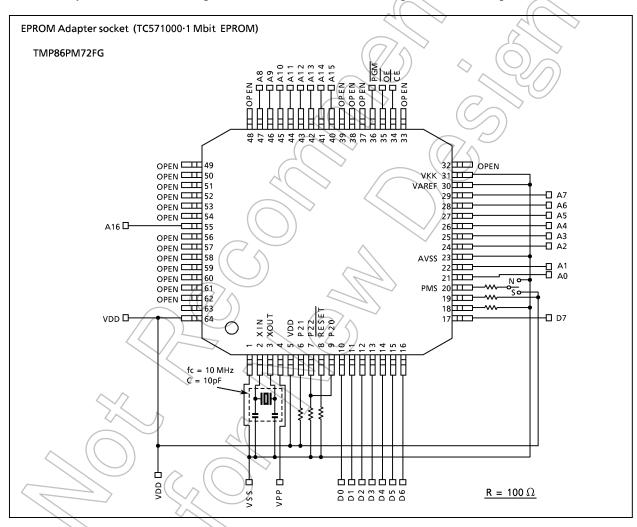


Figure 1-2. PROM Mode Setting

### 1.2.1 Programming Flowchart (High-speed program writing)

The high-speed programming mode is set by applying 12.75 V (programming voltage) to the  $V_{PP}$  pin when the  $V_{DD}$  is 6.25 V. After the address and data are fixed, the data in the address is written by applying 0.1ms of low level program pulse to  $\overline{PGM}$  pin. Then verify if the data is written.

If the programmed data is incorrect, another 0.1 ms pulse is applied to  $\overline{PGM}$  pin.

This programming procedure is repeated until correct data is read from the address (maximum of 25 times).

Subsequently, all data are programmed in all addresses.

When all data were written, verify all address under the condition of  $V_{DD} = V_{PP} = 5 \text{ V}$ .

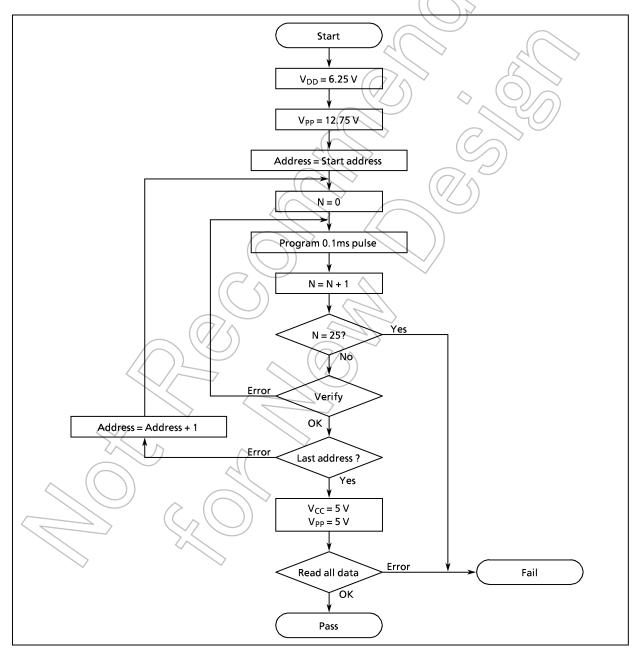


Figure 1-3. Programming Flowchart

86PM72-7 2003-06-23

#### 1.2.2 Program Writing using a General-purpose PROM Programmer

(1) Recommended OTP adapter

BM11707: for TMP86PM72FG

(2) Setting of OTP adapter

Set the switch (SW1) to N side.

- (3) Setting of PROM programmer
  - i) Set PROM type to TC571000D/AD.
     VPP: 12.75 V (high-speed program writing)
  - ii) Data transmission (Note 1)

The PROM of TMP86PM72 is located on different addresses; it depends on operating modes: MCU mode and PROM mode. When you write the data of ROM for mask ROM products, the data should be transferred from the address for MCU mode to that for PROM mode before writing operation is executed. For the applicable program areas of MCU mode and PROM mode are different, refer to Figure 1-1 Program Memory Area.

Example:In the block transfer (copy) mode, executed as below.

ROM capacity of 32 KB: Transferred address  $08000_{\rm H}$  to  $0FFFF_{\rm H}$  to addresses  $00000_{\rm H}$  to  $07FFF_{\rm H}$ 

iii) Setting of the program address (Note 1)

Start address: 00000<sub>H</sub> End address: 07FFF<sub>H</sub>

(4) Writing program

Write and verify according to the above mentioned "Setting of PROM programmer."

- Note 1: For the setting method, refer to each description of PROM programmer.

  Make sure to set the data of address area that is not in used to FF<sub>H</sub>.
- Note 2: When setting MCU to the adapter or when setting the adapter to the PROM programmer, set the first pin of the adapter and that of PROM programmer socket matched. If the first pin is conversely set, MCU or adapter or programmer would be damaged.
- Note 3: The TMP86PM72 does not support the electric signature mode.

  If PROM programmer uses the signature, the device would be damaged because of applying voltage of 12 ± 0.5 V to pin 9 (A9) of the address.

  Do not use the signature.

#### **Electrical Characteristics**

Absolute Maximum Ratings  $(V_{SS} = 0 V)$ 

				2 \	
Parameter		Symbol	Pins	Rating	Unit
Supply voltage		$V_{DD}$		- 0.3 to 6.5	
Program voltage		V <sub>PP</sub>	TEST/V <sub>PP</sub>	- 0.3 to 13.0	
Input voltage		V <sub>IN</sub>		) – 0.3 to V <sub>DD</sub> + 0.3	V
Output voltage		V <sub>OUT1</sub>		- 0.3 to V <sub>DD</sub> + 0.3	
Output voltage		V <sub>OUT2</sub>	Source open drain ports	$V_{DD} - 41 \text{ to } V_{DD} + 0.3$	
	101	I <sub>OUT1</sub>	P0, P1, P2, P4 (P42~P47), P5 ports	5	
Output current (per 1 pin)	IOL	I <sub>OUT2</sub>	P4 (P40, P41) port	40	
		I <sub>OUT3</sub>	P0, P1, P4, P5 ports	73	
	ЮН	I <sub>OUT4</sub>	P6, P7 ports	- 30	mA
		I <sub>OUT5</sub>	P8, P9 ports	-20	
Output current (total)		Σl <sub>OUT1</sub>	P0, P1, P2, P4, P5 ports	120//	
Output current (total)		Σl <sub>OUT2</sub>	P6, P7, P8, P9 ports	- 120	
Power dissipation $[T_{opr} = 2]$	5℃]	PD		1200	mW
Soldering temperature (time)		Tsld		260 (10 μ)	
Storage temperature		Tstg		– 55 to 125	°c
Operating temperature		Topr		– 30 to 70	

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant.

Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.



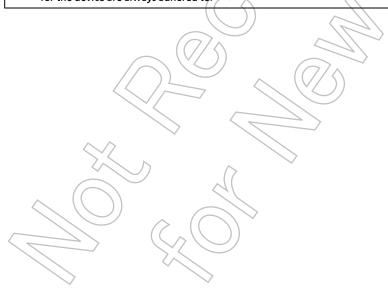
86PM72-9 2003-06-23

**Recommended Operating Condition** 

 $(V_{SS} = 0 \text{ V, Topr} = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Pins	C	ondition	Min	Max	Unit
			6 46 8411	NORMAL1/2 modes	45		
			fc = 16 MHz	IDLE0, 1/2 modes	4.5	) >	
			6 0 0 411	NORMAL1/2 modes		<b>Y</b>	
Supply voltage	$V_{DD}$		fc = 8 MHz	IDLE0, 1/2 modes	$( \langle // \rangle )$	5.5	
		fs =	SLOW mode	2.7			
			32.768 kHz	SLEEP mode			
				STOP mode	<i>\( \)</i>		
Output voltage	V <sub>OUT3</sub>	Source open drain ports			V <sub>DD</sub> - 38	V <sub>DD</sub>	   v
	V <sub>IH1</sub>	Except hysteresis input			$V_{DD} \times 0.70$		
Input high level	V <sub>IH2</sub>	Hysteresis input		(7/4)	$V_{DD} \times 0.75$	V <sub>DD</sub>	
	V <sub>IH3</sub>	TTL input	VD	$_{\rm DD} \le 4.5{\rm V}$	$V_{DD} \times 0.90$	$(U_{\Omega})$	
	V <sub>IL1</sub>	Except hysteresis input				$V_{DD} \times 0.30$	
Input low level	$V_{IL2}$	Hysteresis input			6	$V_{DD} \times 0.25$	
	V <sub>IL3</sub>	TTL input	V <sub>C</sub>	<sub>oD</sub> ≦ 4.5 V	$V_{DD} \times 0.10$	$V_{DD}$	
		VIN VOUT	V <sub>DD</sub>	= 2.7 to 5.5 V		8.0	
Clock frequency	fc	XIN, XOUT	V <sub>DD</sub> :	= 4.5 to 5.5 V	1.0	16.0	MHz
	fs	XTIN, XTOUT			30.0	34.0	kHz

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (Supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.



DC Characteristics (1)

 $(V_{DD} = 5 V)$ 

[Condition]

 $V_{DD} = 5.0 \text{ V} \pm 10\%$ ,  $V_{SS} = A_{VSS} = 0 \text{ V}$ ,  $Topr = -30 \sim 70^{\circ}\text{C}$ (Typ.:  $V_{DD} = 5.0 \text{ V}$ ,  $Topr = 25^{\circ}\text{C}$ , Vin = 5.0 V/0 V)

Parameter	Symbol	Pins	Condition	Min	тур.	Max	Unit
Hysteresis voltage	V <sub>HS</sub>	Hysteresis input	^ (	(7/A)	0.9	-	V
	I <sub>IN1</sub>	TEST					
Input current	I <sub>IN2</sub>	Sink open drain, Tri-st	$V_{DD} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V/0 V}$	-	_	± 2	μΑ
	I <sub>IN3</sub>	RESET, STOP		Ŋ			
Input resistance	R <sub>IN</sub>	RESET pull-up		100	220	450	
Pull-down resistance (Note 4)	R <sub>K</sub>	Source open drain, Tri-st	$V_{DD} = 5.5 \text{ V}, V_{KK} = -30 \text{ V}$	50	80	120	kΩ
Output leakage current	I <sub>LO1</sub>	Sink open drain, Tri-st	$V_{DD} = 5.5 \text{ V}, V_{OUT} = 5.5 \text{ V/0 V}$	0 -(	D) <del>/</del> /~	±2	
Output leakage current	I <sub>LO2</sub>	Source open drain	$V_{DD} = 5.5 \text{ V}, V_{KK} = -32 \text{ V}$	<i>\\</i>	140	± 2	μΑ
Output high voltage	V <sub>OH</sub>	Tri-st port	$V_{DD} = 4.5 \text{ V}, I_{OH} = -0.7 \text{ mA}$	4.1	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	_	V
Output low voltage	V <sub>OL1</sub>	Except XOUT and (P40, P41) Port	$V_{DD} = 4.5 \text{ V}, I_{OL} = 1.6 \text{ mA}$	¥Э)	_	0.4	\ \ \
Output high current	I <sub>OH1</sub>	P6, P7	$V_{DD} = 4.5 \text{ V}, V_{OH} = 2.4 \text{ V}$	- 18	- 28	-	
Output night current	I <sub>OH2</sub>	P8, P9, PD	$V_{DD} = 4.5 \text{ V}, V_{OH} = 2.4 \text{ V}$	) - 9	- 14	-	
Output low current	l <sub>OL</sub>	High current port (P40, P41)	$V_{DD} = 4.5 \text{ V}, V_{OL} = 1.0 \text{ V}$	-	20	-	
Supply current in			fc = 16.0 MHz fs = 32.768 kHz	_	12	18	
NORMAL1/2 modes			fc = 8.0 MHz fs = 32.768 kHz AD converter	_	6	9	mA
Supply current in			fc = 16.0 MHz fs = 32.768 kHz disable (IREF off)	_	6	9	
IDLE0/1/2 modes			fc = 8.0 MHz fs = 32.768 kHz	_	3	4.5	
Supply current in	I <sub>DD</sub>		fc = 16.0 MHz fs = 32.768 kHz AD	_	13	19	
NORMAL1/2 modes			fc = 8.0 MHz fs = 32.768 kHz enable	_	7	10	
Supply current in			Topr = to 50°C AD	_		5	
STOP mode			Topr = to 70°C disable	_	0.5	10	μΑ

Note 1: Typical values show those at Topr =  $25^{\circ}$ C,  $V_{DD} = 5 \text{ V}$ .

Note 2: Input current (I<sub>IN1</sub>, I<sub>IN3</sub>): The current through pull-up or pull-down resistor is not included.

Note 3: IDD does not include IREF current.

Note 4:  $Topr = -10^{\circ}C$  to  $70^{\circ}C$ 

DC Characteristics (2)

 $(V_{DD} = 3 V)$ 

[Condition]

 $V_{DD} = 3.0 \text{ V} \pm 10\%$ ,  $V_{SS} = A_{VSS} = 0 \text{ V}$ ,  $Topr = -30 \text{ to } 70^{\circ}\text{C}$  (Typ.:  $V_{DD} = 3.0 \text{ V}$ ,  $Topr = 25^{\circ}\text{C}$ , Vin = 3.0 V)

	1				+	16		
Parameter	Symbol	Pins	Condition	on	Min	Тур.	Max	Unit
Hysteresis voltage	V <sub>HS</sub>	Hysteresis input		$\wedge$ (2)	/ <u>A</u>	0.4	I	V
	I <sub>IN1</sub>	TEST		7/13				
Input current	I <sub>IN2</sub>	Sink open drain, Tri-st	$V_{DD} = 3.3 \text{ V}, V_{IN} = 3.3 \text{ V}$	3.3 V/0 V	, –	_	± 2	μA
	I <sub>IN3</sub>	RESET, STOP						
Input resistance	R <sub>IN</sub>	RESET pull-up	$\mathcal{A}($		100	220	450	
Pull-down resistance	R <sub>K</sub>	Source open drain, tri-st	$V_{DD} = 3.3 \text{ V, } V_{KK} =$	– 30 V	45	75	115	kΩ
Output leakage current	I <sub>LO1</sub>	Sink open drain, tri-st	$V_{DD} = 3.3 V_{\bullet} V_{OUT}$	= 3.3 V/0 V	-(	2)-	> ± 2	μA
Output leakage current	I <sub>LO2</sub>	Source open drain	$V_{DD} = 3.3 \text{ V}, V_{KK} =$	/ <sub>-32</sub> V	7-1	(4/)	) ± 2	μΑ
Output high voltage	V <sub>OH</sub>	Tri-st port	$V_{DD} = 2.7 \text{ V, } I_{OH} =$	– 0.6 mA	2.3		ı	V
Output low voltage	V <sub>OL1</sub>	Except XOUT and (P40, P41) Port	$V_{DD} = 2.7  V, I_{OL} = 0$	0.9 mA		-	0.4	]
Output high government	I <sub>OH1</sub>	P6, P7	$V_{DD} = 2.7  V, V_{OH} =$	: 1.5 V	5,5	- 8	-	
Output high current	I <sub>OH2</sub>	P8, P9, PD	$V_{DD} = 2.7  V, V_{OH} =$	: 1.5 V	-3	- 4.5	-	
Output low current	l <sub>OL</sub>	High current port (P40, P41) port	$V_{DD} = 2.7  V_{OL} =$	1.0 V	_	6	-	
Supply current in				AD	_	3	4.5	mΑ
NORMAL1/2 modes				converter disable				
Supply current in			L OONALL A	(IREF off)	_	2	2.5	
IDLE0/1/2 modes			$\wedge$	~				
Supply current in			TC = 8.0 IV(HZ	AD converter	_	3.5	5	
NORMAL1/2 modes	I <sub>DD</sub>		fs = 32.768 kHz	enable		3.3		
Supply current in		(7)			_	30	60	
SLOW1 mode			fs = 32.768 kHz	AD				
Supply current in			/ / \ \	converter		15	30	μA
SLEEP0, 1 mode	K /r			disable	_	15	30	] ′
Supply current in	~~ <		Topr = to 50°C		_	0.5	5	
STOP mode			Topr = to 70℃			0.5	10	

Note 1: Typical values show those at Topr =  $25^{\circ}$ C,  $V_{DD} = 3 \text{ V}$ .

Note 2: Input current (I<sub>IN1</sub>, I<sub>IN3</sub>): The current through pull-up or pull-down resistor is not included.

Note 3: IDD does not include IREF current.

Note 4: The supply currents of SLOW2 and SLEEP2 modes are equivalent IDLE0, 1, 2.

## **AD Conversion Characteristics**

(Vss = 0.0 V, 4.5 V  $\, \leq \,$  V\_DD  $\, \leq \,$  5.5 V, Topr =  $\,$  – 30 to 70°C)

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog reference voltage	V <sub>AREF</sub>		V <sub>DD</sub> - 1.5	7->	$V_{DD}$	
Analog reference GND	A <sub>VSS</sub>			V <sub>SS</sub>		l
Analog reference voltage range (Note 4)	$\triangle V_{AREF}$		(3.0)	_	-	\ \
Analog input voltage	V <sub>AIN</sub>		Vss	) -	V <sub>AREF</sub>	
Power supply current of analog reference voltage	I <sub>REF</sub>	$V_{DD} = V_{AREF} = 5.5 V$ $V_{SS} = AV_{SS} = 0.0 V$	\\\	0.6	1.0	mA
Non linearity error			$\bigcirc$ $\nearrow$	-	± 1	
Zero point error		$V_{DD} = V_{AREF} = 4.5 \text{ to } 5.0 \text{ V},$	<u> </u>	- (	±1	LSB
Full scale error		$V_{SS} = A_{VSS} = 0.0 V$	-	7(	±1	LOB
Total error			_	7	± 2	

(Vss = 0.0 V, 2.7 V  $\leq$  VDD < 4.5 V, Topr = - 30 to 70°C)

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog reference voltage	V <sub>AREF</sub>	4	V <sub>DD</sub> - 1.5	<u> -</u>	$V_{DD}$	
Analog reference GND	A <sub>VSS</sub>			V <sub>SS</sub>		] ,,
Analog reference voltage range (Note 4)	$\triangle V_{AREF}$		7,2,5	-	-	\ \
Analog input voltage	VAIN		V <sub>SS</sub>	-	V <sub>AREF</sub>	
Power supply current of analog reference voltage	I <sub>REF</sub>	$V_{DD} = V_{AREF} = 4.5 V$ $V_{SS} = A_{VSS} = 0.0 V$	)-	0.5	0.8	mA
Non linearity error			-	-	± 1	
Zero point error		$V_{DD} = A_{VDD} = 2.7 \text{ V to } 4.5 \text{ V}$ $V_{SS} = A_{VSS} = 0.0 \text{ V}$	-	-	± 1	LSB
Full scale error		$V_{SS} = A_{VSS} = 0.0 \text{ V}$	-	-	± 1	1 136
Total error			_	-	± 2	

- Note 1: The total error includes all errors except a quantization error, and is defined as a maximum deviation from the ideal

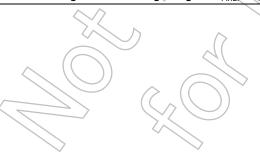
- Note 2: Conversion time is different in recommended value by power supply voltage.

  About conversion time, please refer to "2.11.2 Register Configuration".

  Note 3: Please use input voltage to AIN input Pin in limit of V<sub>AREF</sub> V<sub>SS</sub>.

  When voltage of range outside is input, conversion value becomes unsettled and gives affect to other channel conversion value.

  Note 4: Analog Reference Voltage Range:  $\triangle V_{AREF} = V_{AREF} - V_{SS}$



## **AC Characteristics**

 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, Topr = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL1/2 modes	((			
Machine cycle time	4	IDLE1/2 modes	0.25		4	
	tcy	SLOW1/2 modes	$(\Omega I)$	) -	133.3	μS
		SLEEP1/2 modes	117.6			
High level clock pulse width	twcH	For external clock operation (XIN input)				ns
Low level clock pulse width	twcL	fc = 16 MHz	15	31.25	_	115
High level clock pulse width	twcH	For external clock operation (XTIN input)		45.00		
Low level clock pulse width	twcL	fc = 32.768 kHz	_	15.26	\ <u>_</u>	μS

$$(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 4.5 \text{ V}, \text{Topr} = -30 \text{ to } 70^{\circ}\text{C})$$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Machine cycle time tcy		NORMAL1/2 modes IDLE1/2 modes	0.5	<del>-</del>	8	
	tcy	SLOW1/2 modes SLEEP1/2 modes	7117.6	<del>-</del>	133.3	μS
High level clock pulse width	twcH	For external clock operation (XIN input)				ns
Low level clock pulse width	twcL	fc = 8 MHz	_	62.5	_	115
High level clock pulse width	twcH	For external clock operation (XTIN input)		15.26		μS
Low level clock pulse width	twcL	fc = 32.768 kHz	_	15.26	-	μ3



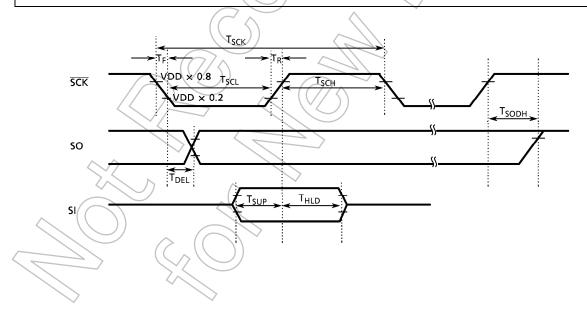
**HSIO AC Characteristics** 

(Vss = 0 V, 2.7 V  $\leq$  VDD  $\leq$  5.5 V, Topr = – 30 to 70  $^{\circ}\!\!$  C )

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
SCK output period (Internal clock)	T <sub>SCK1</sub>		16/fc	1-/	-	
SCK output low width (Internal clock)	T <sub>SCL1</sub>	8 MHz < fc $\leq$ 16 MHz V <sub>DD</sub> = 4.5 V to 5.5 V	8/fc – 100ns	$\bigcirc$ Y	-	
SCK output high width (Internal clock)	T <sub>SCH1</sub>	- V <sub>DD</sub> = 4.3 V to 3.3 V	8/fc - 100ns	<u>_</u>	-	
SCK output period (Internal clock)	T <sub>SCK2</sub>	4444	8/fc/	) -	-	
SCK output low width (Internal clock)	T <sub>SCL2</sub>	4  MHz < fc ≤ $8  MHzV_{DD} = 2.7 \text{ V to } 5.5 \text{ V}$	4/fc - 100ns	-	_	s
SCK output high width (Internal clock)	T <sub>SCH2</sub>	- V <sub>DD</sub> - 2.7 V to 3.3 V	4/fc - 100ns	-	_	
SCK output period (Internal clock)	T <sub>SCK3</sub>		4/fc	-	-	
SCK output low width (Internal clock)	T <sub>SCL3</sub>	$fc \le 4 \text{ MHz}$ $V_{DD} = 2.7 \text{ V to } 5.5 \text{ V}$	2/fc - 100ns	- (	-	
SCK output high width (Internal clock)	T <sub>SCH3</sub>	- V <sub>DD</sub> = 2.7 V to 3.5 V	2/fc - 100ns	-1(	1/-	
SCK input period (External clock)	T <sub>SCK4</sub>	fc ≤ 8 MHz	800	0	-	
SCK input low width (External clock)	T <sub>SCL4</sub>	$(V_{DD} = 2.7 \text{ V to } 5.5 \text{ V})$ fc $\leq 16 \text{ MHz}$	300 (Note 1)	(3)	<b>&gt;</b> -	ns
SCK input low width (External clock)	T <sub>SCH4</sub>	$(V_{DD} = 4.4 \text{ V to } 5.5 \text{ V})$	300 (Note 1)	9//	<u> </u>	
SI input setup time	T <sub>SUP</sub>		150	7-70	// -	
SI input hold time	T <sub>HLD</sub>		150	130	_	
SO output delay time	T <sub>DEL</sub>	4( \>	-(0)	)) <b>-</b>	200	
Rising time	T <sub>R</sub>	$V_{DD} = 3.0 \text{ V, CL} = 50 \text{pF}$		/ <b>-</b>	100	ns
Falling time	T <sub>F</sub>	(Note 2)	(7/1	-	100	1
SO last bit hold time	T <sub>SODH</sub>		16.5/fc	-	32.5/fc	

Note 1: T<sub>SCKL</sub>, T<sub>SCKH</sub> ≥ 2.5/fc (High-frequency clock mode), T<sub>SCKL</sub>, T<sub>SCKH</sub> ≥ 2.5/fc (Low-frequency clock mode)

Note 2: CL, external capacitance



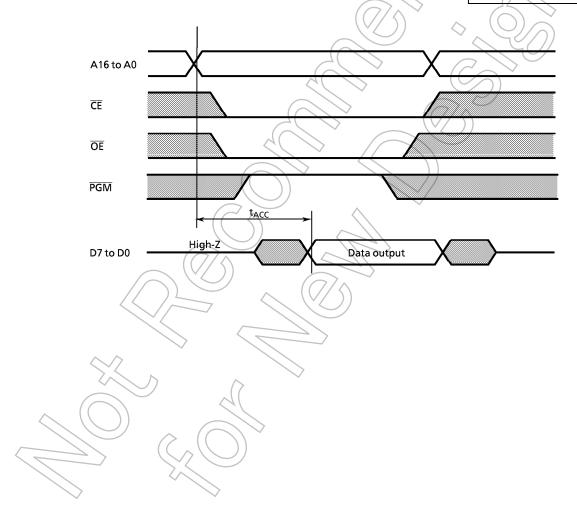
DC Characteristics, AC Characteristics (PROM mode)

 $(V_{SS} = 0 \text{ V, Topr} = 25 \pm 5^{\circ}\text{C})$ 

## (1) Read operation in PROM mode

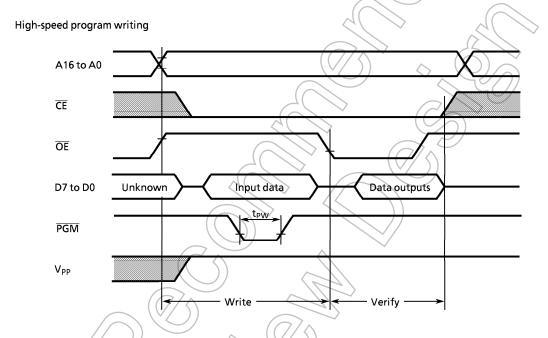
Parameter	Symbol	Conditions	Min	Týp.	Max	Unit
High level input voltage (TTL)	V <sub>IH3</sub>		2.2		V <sub>DD</sub>	
Low leve input voltage (TTL)	V <sub>IL3</sub>		0	$\left( \left\langle \left\langle \right\rangle \right\rangle \right)$	0.8	.,
Power supply	$V_{DD}$		4.75	5.0	5.25	V
Power supply of program	$V_{PP}$		4,73	) > 3.0	5.25	
Address access time	t <sub>ACC</sub>	V <sub>DD</sub> = 5.0 ± 0.25 V		1.5tcyc + 300		ns

Note: tcyc = 400 ns at 10 MHz



## (2) Program operation (High-speed) (Topr = $25 \pm 5^{\circ}$ C)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
High level input voltage (TTL)	V <sub>IH3</sub>		2.2	<del>(</del> )	$V_{DD}$	
Low leve input voltage (TTL)	V <sub>IL3</sub>		0		0.8	V
Power supply	$V_{DD}$		6.0	6.25	6.5	\ \
Power supply of program	V <sub>PP</sub>		12.5	12.75	13.0	
Pulse width of initializing program	t <sub>PW</sub>	V <sub>DD</sub> = 6.0 V	0.095	0.1	0.105	ms



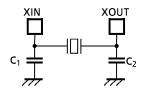
- Note 1: The power supply of  $V_{PP}$  (12.75 V) must be set power-on at the same time or the later time for a power supply of  $V_{DD}$  and must be clear power-on at the same time or early time for a power supply of  $V_{DD}$ .
- Note2: The pulling up/down device on the condition of  $V_{PP} = 12.75 \text{ V } \pm 0.25 \text{ V}$  causes a damage for the device. Do not pull up/down at programming.
- Note3: Use the recommended adapter and mode.

  Using other than the above condition may cause the trouble of the writting.

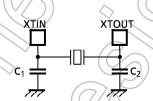
**Recommended Oscillating Conditions** 

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Oscillator	Oscillation Frequency	VDD	Recommended Oscillator	Recommend C <sub>1</sub>	ed Constant C <sub>2</sub>
High-frequency oscillation Ceramic resonate		16 MHz	4.5 V to 5.5 V	MURATA CSA16.00MXZ040	10 pF	10 pF
	Ceramic resonator	8 MHz	2.7 V to 5.5 V	MURATA CSA8.00MTZ CST8.00MTW	30 pF 30 pF (built-in)	30 pF 30 pF (built-in)
		4.19 MHz	2.7 V to 5.5 V	MURATA CSA4.19MG CST4.19MGW	30 pF 30 pF (built-in)	30 pF 30 pF (built-in)
Low-frequency oscillation	Crystal oscillator	32.768 kHz	2.7 V to 5.5 V	SII VT-200	6 pF	6 pF



(1) High-frequency Oscillation



(2) Low-frequency Oscillation

- Note 1: An electrical shield by metal shield plate on the surface of IC package is recommended in order to protect the device from the high electric field stress applied from CRT (Cathodic Ray Tube) for continuous reliable operation.
- Note2: When using the device (oscillator) in places exposed to high electric fields such as cathode-ray tubes, we recommend electrically shielding the package in order to maintain normal operating condition.
- Note 3: The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change.

  For up-to-date information, please refer to the following URL;

  http://www.murata.co.jp/search/index.html

